

Przemyslaw Rupnowski

List of Publications by Year in descending order

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24
papers

346
citations

933447

10
h-index

794594

19
g-index

24
all docs

24
docs citations

24
times ranked

347
citing authors

#	ARTICLE	IF	CITATIONS
1	Strength of silicon wafers: fracture mechanics approach. International Journal of Fracture, 2009, 155, 67-74.	2.2	58
2	In-plane shear testing of medium and high modulus woven graphite fiber reinforced/polyimide composites. Composites Science and Technology, 2004, 64, 203-220.	7.8	56
3	An evaluation of the elastic properties and thermal expansion coefficients of medium and high modulus graphite fibers. Composites Part A: Applied Science and Manufacturing, 2005, 36, 327-338.	7.6	33
4	Mechanical response of a unidirectional graphite fiber/polyimide composite as a function of temperature. Composites Science and Technology, 2006, 66, 1045-1055.	7.8	29
5	Visco-elastic stress distributions and elastic properties in unidirectional composites with large volume fractions of fibers. Acta Materialia, 2003, 51, 3483-3493.	7.9	26
6	Meso- and micro-stress analyses in an 8HS graphite/polyimide woven composite subjected to biaxial in-plane loads at room temperature. Composites Science and Technology, 2003, 63, 785-799.	7.8	21
7	Performance Limitations of mc-Si Solar Cells Caused by Defect Clusters. ECS Transactions, 2009, 18, 1049-1058.	0.5	21
8	X-ray diffraction experiments on aged graphite fiber/polyimide composites with embedded aluminum inclusions. Composites Part A: Applied Science and Manufacturing, 2004, 35, 667-681.	7.6	19
9	Mechanical response of a woven graphite/polyimide composite to in-plane shear dominated loads at room and elevated temperatures. Acta Materialia, 2004, 52, 5603-5613.	7.9	15
10	“The development of a through-plane reactive excitation technique for detection of pinholes in membrane-containing MEA sub-assemblies” International Journal of Hydrogen Energy, 2019, 44, 8533-8547.	7.1	13
11	Wafer preparation and iodine-ethanol passivation procedure for reproducible minority-carrier lifetime measurement. Conference Record of the IEEE Photovoltaic Specialists Conference, 2008, , .	0.0	8
12	Studies on Backside Al-Contact Formation in Si Solar Cells: Fundamental Mechanisms. Materials Research Society Symposia Proceedings, 2008, 1123, 11.	0.1	8
13	Light-Induced Passivation of Si by Iodine Ethanol Solution. Materials Research Society Symposia Proceedings, 2008, 1123, 10.	0.1	6
14	In-line monitoring of Li-ion battery electrode porosity and areal loading using active thermal scanning - modeling and initial experiment. Journal of Power Sources, 2018, 375, 138-148.	7.8	6
15	Studies on Backside Al-Contact Formation in Si Solar Cells: Fundamental Mechanisms. , 2008, , .		6
16	The response of a woven graphite fiber/polyimide composite to aging in nitrogen. Acta Materialia, 2005, 53, 4555-4565.	7.9	4
17	A new method for rapid measurement of orientations and sizes of grains in multicrystalline silicon wafers. , 2011, , .		4
18	Calculations of J integrals around fractal defects in plates. International Journal of Fracture, 2001, 111, 381-394.	2.2	3

#	ARTICLE	IF	CITATIONS
19	Dislocation Generation in Si: A Thermo-Mechanical Model Based on Measurable Parameters. , 2006, , .		3
20	Spectroscopic Investigation of Catalyst Inks and Thin Films Toward the Development of Ionomer Quality Control. Applied Spectroscopy, 2022, 76, 644-659.	2.2	3
21	A New, Ultrafast Technique for Mapping Dislocation Density in Large-area, Single-crystal and Multicrystalline Si Wafers. Materials Research Society Symposia Proceedings, 2009, 1210, 1.	0.1	2
22	Strength of Multicrystalline Silicon Wafers for Various Surface Conditions. Materials Research Society Symposia Proceedings, 2009, 1210, 1.	0.1	1
23	A high throughput, noncontact system for screening silicon wafers predisposed to breakage during solar cell production. , 2011, , .		1
24	Strength of Si wafers with microcracks: A theoretical model. Conference Record of the IEEE Photovoltaic Specialists Conference, 2008, , .	0.0	0